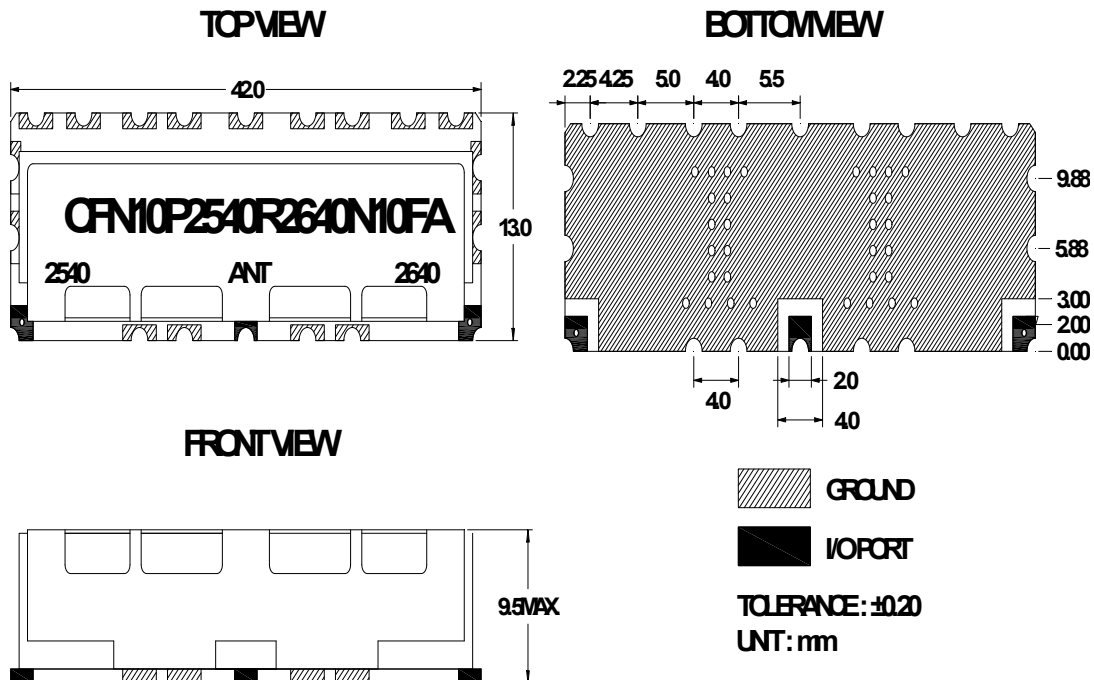


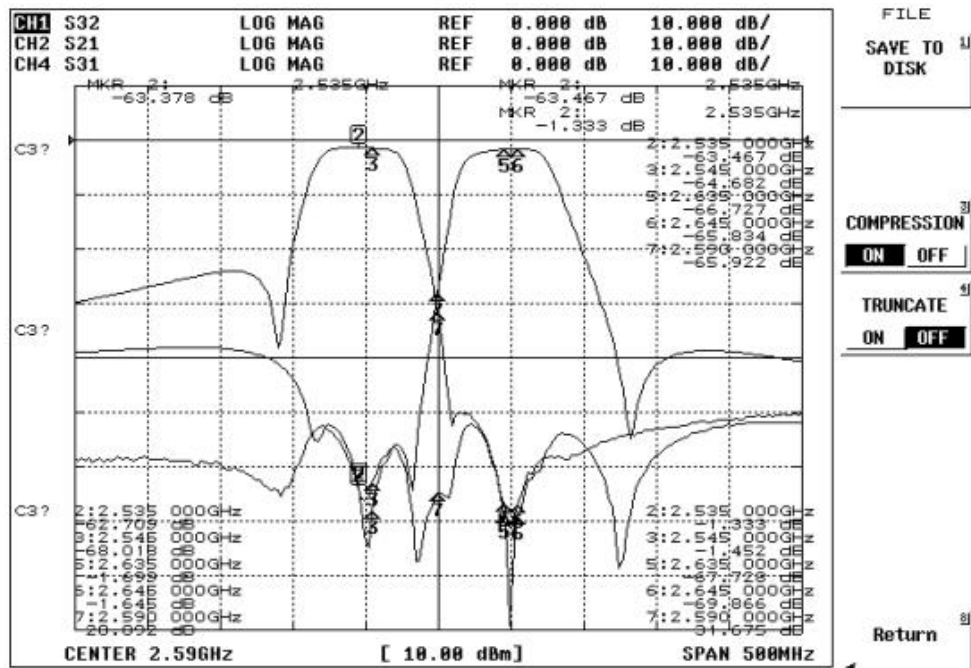
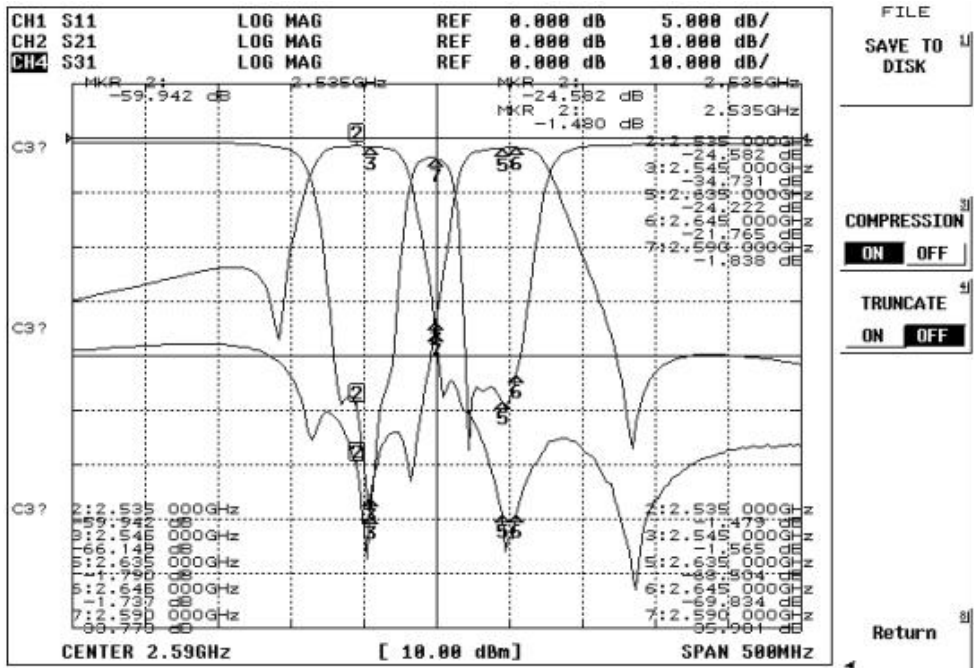
Electrical Specification

ITEMS	ANT >> Low	ANT >> High	UNIT
Center Frequency [fo]	2540.0	2640.0	MHz
Bandwidth [BW]	fo ±5.0 [2535.0~2545.0]	fo ±3.5 [2635.0~2645.0]	MHz
Insertion Loss in BW	2.0	2.0	dB max
Ripple in BW	1.0	1.0	dB max
Return Loss in BW			dB min
Attenuation	50.0 dBmin. @ [2635~2645]	50.0dBmin.@ [2535~2545]	MHz
<input checked="" type="checkbox"/> Absolute Value	25.0 dBmin. @ [2590~]	25.0dBmin.@ [2590~]	MHz
<input type="checkbox"/> Relative Value	dBmin. @ [~]	dBmin.@ [~]	MHz
	dBmin. @ [~]	dBmin.@ [~]	MHz
Group Delay Variation			ns max
Input Power	3.0		W max.
In/Out Impedance	50 Ω		
Operation Temperature Range	-40°C to +85°C		

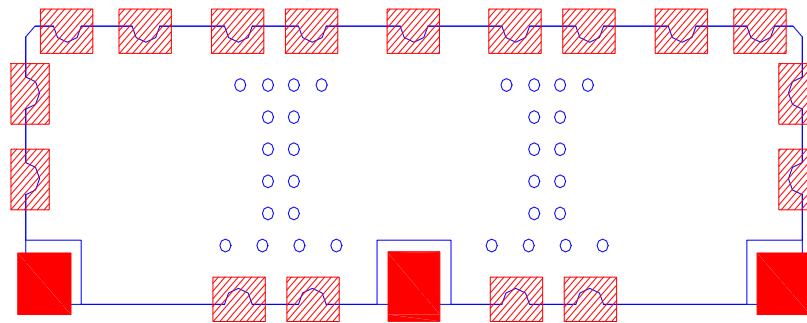
Mechanical Specification



Plot Data

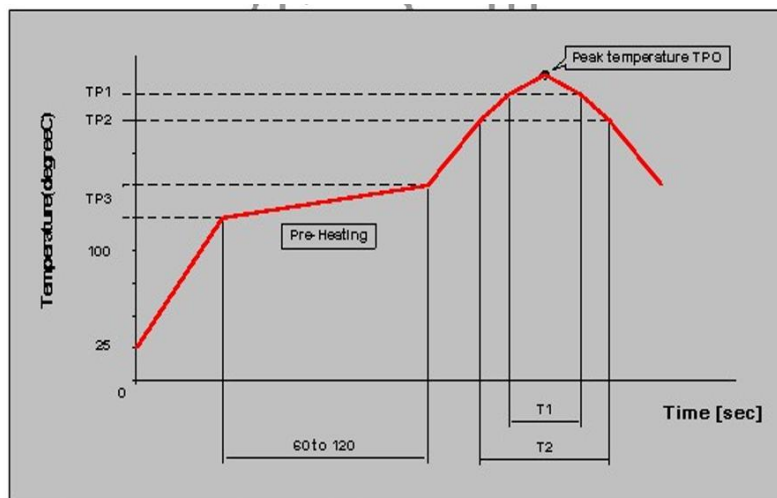


Recommended PC Board Pattern



 **I/O PORT SOLDERING POINT**
 **GROUND SOLDERING POINT**

Soldering Condition



Measuring point of temperature : IN-OUT Terminals of The Device

Reflow Soldering : Both Convection and Infrared Rays, Hot Air and Hot Plate

Reflow standard condition	TP0 (°C)	TP1 (°C)	T1 (s)	TP2 (°C)	T2 (s)	TP3 (°C)
Sn-3Ag-0.5 solder	245+/-5	220	30 to 60	—	—	150 to 180
Test condition of reflow heat resistance	260+5/-0	240	20	220	70	150 to 180